

UC2856Q SGLS265-NOVEMBER 2004

# IMPROVED CURRENT MODE PWM CONTROLLER

## **FEATURES**

- Pin-for-Pin Compatible With the UC2846
- 65-ns Typical Delay From Shutdown to Outputs and 50-ns Typical Delay From Sync to Outputs
- Improved Current Sense Amplifier With Reduced Noise Sensitivity
- Differential Current Sense With 3-V
  Common Mode Range
- Trimmed Oscillator Discharge Current for Accurate Deadband Control
- Accurate 1-V Shutdown Threshold
- High Current Dual Totem Pole
   Outputs (1.5-A peak)
- TTL Compatible Oscillator SYNC Pin Thresholds
- 4-kV ESD Protection

## DESCRIPTION

The UC2856 is a high performance version of the popular UC2846 series of current mode controllers, and is intended for both design upgrades and new applications where speed and accuracy are important. All input to output delays have been minimized, and the current sense output is slew rate limited to reduce noise sensitivity. Fast 1.5-A peak output stages have been added to allow rapid switching of power FETs.

A low impedance TTL compatible sync output has been implemented with a 3-state function when used as a sync input.

Internal chip grounding has been improved to minimize internal *noise* caused when driving large capacitive loads. This, in conjunction with the improved differential current sense amplifier, results in enhanced noise immunity.

Other features include a trimmed oscillator current (8%) for accurate frequency and dead time control; a 1 V, 5% shutdown threshold; and 4 kV minimum ESD protection on all pins.

T <sub>A</sub>	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING

Tape and reel

UC2856QDWR

#### ORDERING INFORMATION<sup>(1)</sup>

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

SOP-DW



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

-40°C to 125°C

UC2856Q



P0008-01

#### **BLOCK DIAGRAM**



B0010-01

## **ORDERING INFORMATION**



#### **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range (unless otherwise noted)<sup>(1)(2)</sup>

			UNIT
	Supply voltage	40 V	
	Collector supply voltage	40 V	
	Output current (sink or source)	DC	0.5 A
1 <sub>0</sub>		Pulse (0.5 ms)	2 A
	Error amplifier input voltage		-0.3 V to VIN
	Shutdown input voltage		–0.3 V to 10 V
	Current sense input voltage	-0.3 V to 3 V	
	SYNC output current	±10 mA	
	Error amplifier output current	-5 mA	
	Soft start sink current		50 mA
	Oscillator charging current		5 mA
	Dower dissinction	$T_A = 25^{\circ}C$	1 W
	Power dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	2 W
TJ	Operating junction temperature rai	–55°C to 150°C	
T <sub>stg</sub>	Storage temperature range	–65°C to 150°C	
	Lead temperature soldering 1,6 m	300°C	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

## **ELECTRICAL CHARACTERISTICS**

 $T_A = -40^{\circ}C$  to 125°C, VIN = 15 V, RT = 10 k $\Omega$ , CT = 1 nF, and  $T_A = T_J$  (unless otherwise stated)<sup>(1)</sup>

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
REFERENCE SECTION							
Output voltage	$I_{O} = 1 \text{ mA}, \qquad T_{J} = 25^{\circ}\text{C}$	5.05	5.1	5.15	V		
Line regulation voltage	VIN = 8 V to 40 V			20	mV		
Load regulation voltage	$I_{O} = -1 \text{ mA to } -10 \text{ mA}$			15	mV		
Total output variation	Line, Load, and Temperature	5		5.2	V		
Output noise voltage	$f = 10 \text{ Hz to } 10 \text{ kHz}, \qquad T_J = 25^{\circ}\text{C}$		50		μV		
Long term stability	1000 hours, <sup>(2)</sup> $T_J = 25^{\circ}C$		5	25	mV		
Short circuit current	VREF = 0 V	-25	-45	-65	mA		
OSCILLATOR SECTION							
Initial accuracy	$T_J = 25^{\circ}C$	180	200	220			
	T <sub>J</sub> = Full range	170		230	230		
Voltage stability	VIN = 8 V to 40 V			2%			
Discharge surrent	$VCT = 2 V,$ $T_J = 25^{\circ}C$	7.5	8	8.8			
Discharge current	VCT = 2 V	6.7	8	8.8	mA		
Sync output high level voltage	$I_{O} = -1 \text{ mA}$	2.4	3.6		V		
Sync output low level voltage	I <sub>O</sub> = 1 mA		0.2	0.4	V		
Sync input high level voltage	CT = 0 V, RT = VREF	2	1.5		V		
Sync input low level voltage	CT = 0 V, RT = VREF		1.5	0.8	V		
Sync input current	CT = 0 V, RT = VREF, V <sub>SYNC</sub> = 5 V		1	10	μA		
Sync delay to outputs	$CT = 0 V RT = VREF$ , $V_{SYNC} = 0.8 V$ to 2 V		50	100	ns		

(1) All voltages are with respect to GND. Currents are positive into, negative out of the specified terminal.

(2) This parameter, although specified over the recommended operating conditions, is not 100% tested in production.

## **ELECTRICAL CHARACTERISTICS (continued)**

 $T_{\rm A}$  = –40°C to 125°C, VIN = 15 V, RT = 10 k\Omega, CT = 1 nF, and  $T_{\rm A}$  =  $T_{\rm J}$  (unless otherwise stated)

PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT	
ERROR AMPLIFIER SECTION							
Input offset voltage	$V_{CM} = 2 V$				5	mV	
Input bias current					-1	μA	
Input offset current					500	nA	
Common mode range	VIN = 8 V to 40 V		0		VIN-2	V	
Open loop gain	$V_0 = 1.2 \text{ V to } 3 \text{ V}$		80	100		dB	
Unity gain bandwidth	$T_J = 25^{\circ}C$		1	1.5		MHz	
CMRR	$V_{CM} = 0 V \text{ to } 38 V,$	VIN = 40 V	75	100		dB	
PSRR	VIN = 8 V to 40 V		80	100		dB	
Output sink current	V <sub>ID</sub> = -15 mV	V <sub>COMP</sub> = 1.2 V	5	10		mA	
Output source current	V <sub>ID</sub> = 15 mV	$V_{COMP} = 2.5 V$	-0.4	-0.5		mA	
High-level output voltage	V <sub>ID</sub> = 50 mV,	$R_L$ (COMP) = 15 k $\Omega$	4.3	4.6	4.9	V	
Low-level output voltage	V <sub>ID</sub> = -50 mV,	$R_L$ (COMP) = 15 k $\Omega$		0.7	1	V	
CURRENT SENSE AMPLIFIER SECTION		· · · ·					
Amplifier gain	$V_{CS-} = 0 V,$	CL SS Open <sup>(3)(4)</sup>	2.5	2.75	3	V/V	
Maximum differential input signal (V <sub>CS+</sub> - V <sub>CS-</sub> )	CL SS Open 3,	$R_L$ (COMP) = 15 k $\Omega$	1.1	1.2		V	
Input offset voltage	V <sub>CL SS</sub> = 0.5 V	COMP open <sup>(5)</sup>		5	35	mV	
CMRR	$V_{CM} = 0 V \text{ to } 3 V$		60			dB	
PSRR	VIN = 8 V to 40 V		60			dB	
Input bias current	V <sub>CL SS</sub> = 0.5 V,	COMP open <sup>(5)</sup>			-1	μΑ	
Input offset current	V <sub>CL SS</sub> = 0.5 V,	COMP open <sup>(5)</sup>			1	mA	
Input common mode range			0		3	V	
Delay to outputs	$V_{EA+} = VREF, EA- = 0 V, C$	CS+ – CS– = 0 V to 1.5 V		120	250	ns	
CURRENT LIMIT ADJUST SECTION							
Current limit offset	$V_{CS-} = 0 V, V_{CS+} = 0 V,$	COMP Open <sup>(5)</sup>	0.4	0.5	0.6	V	
Input bias current	V <sub>EA+</sub> = VREF,	$V_{EA-} = 0 V$		-10	-30	μA	
SHUTDOWN TERMINAL SECTION							
Threshold voltage			0.95	1.00	1.05	V	
Input voltage range			0		5	V	
Minimum latching current (I <sub>CL SS</sub> )			(6)3	1.5		mA	
Maximum non-latching current (I <sub>CL SS</sub> )				<sup>(7)</sup> 1.5	0.8	mA	
Delay to outputs	$V_{SHUTDOWN} = 0 V \text{ to } 1.3 V$			65	110	ns	
OUTPUT SECTION							
Collector-emitter voltage			40			V	
Off-state bias current	VC = 40 V				250	μA	
Output low lovel voltage	I <sub>OUT</sub> = 20 mA			0.1	0.5	V	
Output low level voltage	I <sub>OUT</sub> = 200 mA			0.5	2.6	v	
Quitaut high lovel voltage	$I_{OUT} = -20 \text{ mA}$		12.5	13.2		1/	
	I <sub>OUT</sub> = -200 mA		12	13.1		v	
Rise time	C1 = 1 nF			40	80	ns	
Fall time	C1 = 1 nF			40	80	ns	

(3) Parameter measured at trip point of latch with VEA+ = VREF, VEA- = 0 V.  $\Delta V$  = 2.2.

$$_{SC} G = \frac{\Delta V_{COMP}}{\Delta V_{CS}}; \Delta V_{CS} - = 0 V 1 V$$

(4) Amplifier gain defined as:  $\Delta V C$ 

(5) Parameter measured at trip point of latch with VEA+ = VREF, VEA- = 0 V.

(6) Current into CL SS assured to latch circuit into shutdown state.

(7) Current into CL SS assured not to latch circuit into shutdown state.



## **ELECTRICAL CHARACTERISTICS (continued)**

 $T_A = -40^{\circ}C$  to 125°C, VIN = 15 V, RT = 10 k $\Omega$ , CT = 1 nF, and  $T_A = T_J$  (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT		
UVLO low saturation	VIN = 0 V,	I <sub>OUT</sub> = 20 mA		0.8	1.5	V		
PWM SECTION	PWM SECTION							
Maximum duty cycle			45%	47%	50%			
Minimum duty cycle					0%			
UNDERVOLTAGE LOCKOUT SECTION								
Startup threshold				7.7	8			
Threshold hysterisis				0.7				
TOTAL STANDBY CURRENT	·				·			
Supply current				18	23	mA		

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#### **APPLICATION AND OPERATION INFORMATION**



NOTE: Output deadtime is determined by the size of the external capacitor, C<sub>T</sub>, according to the formula:  $Td = \frac{1}{4}$ For large values of R<sub>T</sub>:  $Td = 250 C_T$ Oscillator frequency is approximated by the formula:  $f_T = \frac{2}{R_T \times C_T}$ 



#### S0019-01









Figure 3. Error Amplifier Gain and Phase vs Frequency



### **APPLICATION AND OPERATION INFORMATION (continued)**



Figure 4. Error Amplifier Open-Loop DC Gain vs Load Resistance



NOTE: Slaving allows parallel operation of two or more units with equal current sharing.

Figure 5. Parallel Operation



## **APPLICATION AND OPERATION INFORMATION (continued)**



Figure 6. Pulse by Pulse Current Limiting



#### **APPLICATION AND OPERATION INFORMATION (continued)**



NOTE: If V<sub>REF</sub> / R1 < 0.8 mA, the shutdown latch commutates when I<sub>SS</sub> = 0.8 mA and a restart cycle will be initiated. If V<sub>REF</sub> / R1 > 3 mA, the device will latch off until power is recycled.

#### Figure 7. Shutdown



#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins F	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UC2856QDWR	ACTIVE	SOIC	DW	16	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AA.



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